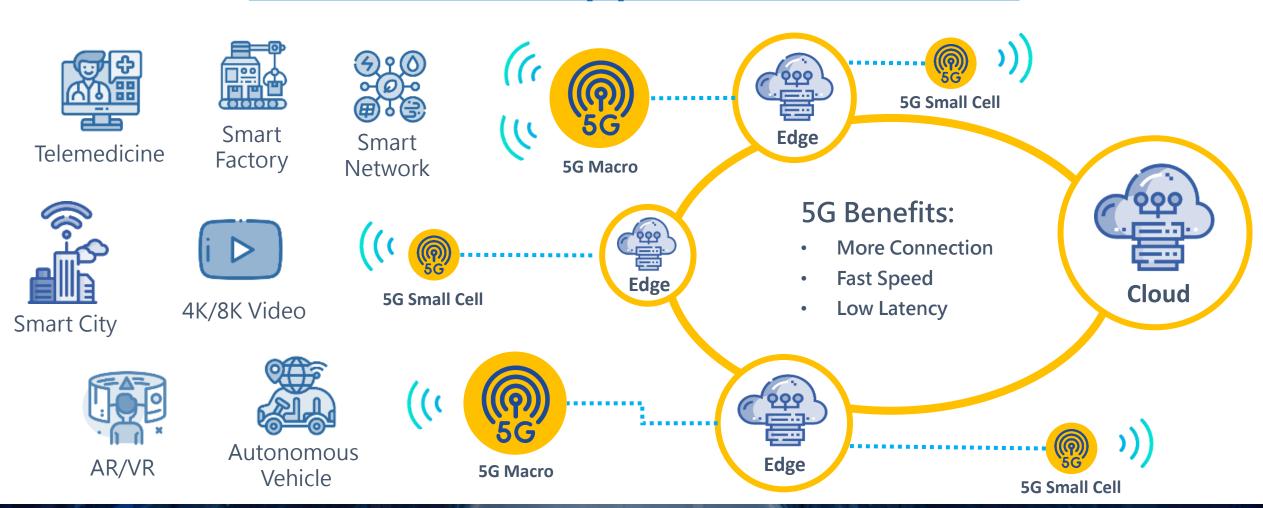


Presenters:

- · Alber Wu, Server Business unit, Division Director, ASUS
- Oren Benisty, EVP Strategic Sales, Silicom



New Market Opportunities on 5G





3-Way Cooperation for 5G Edge

"5G is expected to unleash a massive IoT ecosystem where networks can serve communication needs for billions of connected devices, with the right trade-offs between speed, latency and cost."

Excellent Server Design Ability "Intel-powered 5G networks deliver a powerful data-centric future where computer is fluid, intelligent, and pervasive-creating an evolutionary leap in agility and scalability."

5G Networking
Solution

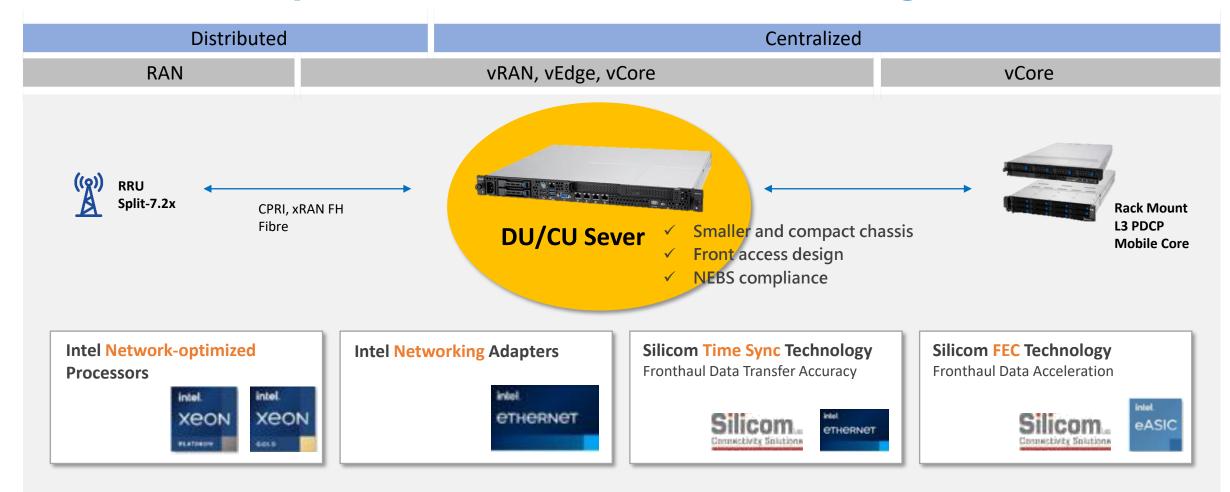
5G Edge



Intel, the Intel logo, and other Intel marks are trademarks of Intel Corporation or its subsidiaries.



Open RAN Server Joint Design

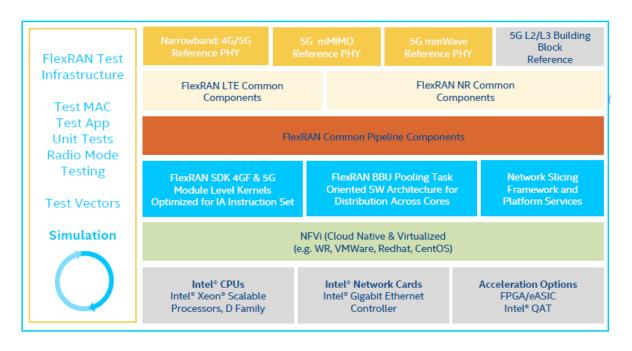


 ${\it Intel, the Intel logo, and other Intel marks are trademarks of Intel Corporation or its subsidiaries.}$



Intel 5G Solutions

FlexRAN Architecture



"Intel 5G Solutions Distribute the Power and Intelligence of the Data Center from Cloud to Network to Edge"



Intel, the Intel logo, and other Intel marks are trademarks of Intel Corporation or its subsidiaries.



Silicom 5G PCIe cards for 4G/5G

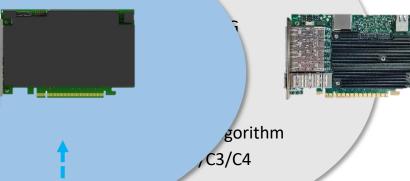
Silicom ACCC

- FEC Ac
- Sur
- 9
- •

Silicom 5G SmartNIC

- FPGA Arria10/AgileX and MAC
- L1 Acceleration
- Time Sync 1588/SyncE
- OCXO for Hold Over
- 8 port 10G/25G or 2*100G
- GNSS receiver Grand Master
- Boundary / Transparent mode
- BMCA Best Master Clock Algorithm
- Support O-RAN LLS C1/C2/C3/C4











ASUS Server Core Competency



Performance



Green Computing



Thermal Optimized



Security



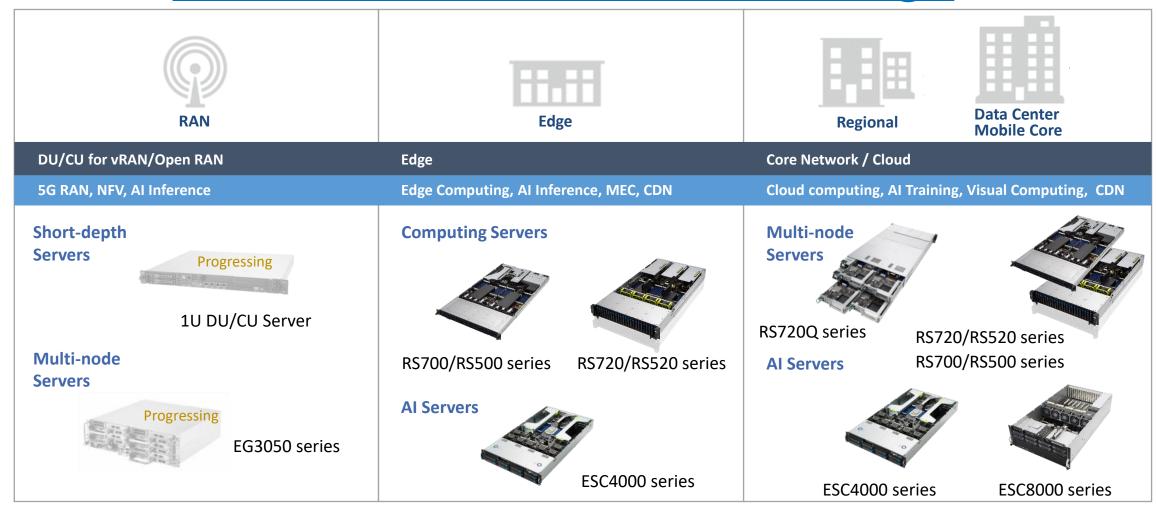
Reliability



Server Management



ASUS Servers From Cloud to Edge





ASUS Servers Proposed for Cloud and Edge

Next Gen
AST2600
BMC Hardware

Performance
Tuning
Setup & Deploy
via BMC

Balanced
Design
between Two CPUs

Next Gen

ASMB 10

BMC Software

PCle 4.0
Twice Fast
Speed

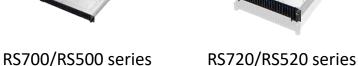
PFR option for BIOS / BMC Protection

Water Cooling
Open-Loop
Solution Ready

OCP 3.0 Up to 200Gbps More Storage
Bays and
All NVMe
Support

Rack Servers for Cloud Computing & Edge Computing







RS720Q series

GPU Optimized Servers for AI Training & AI Inference



ESC4000 series



ESC8000 series

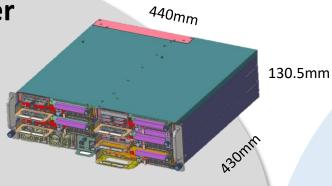




ASUS Servers Proposed For 5G Edge

ASUS EG3050 5G Edge Server

- Compact short-depth design
- High power efficiency
- All-in-One architecture with:
 - Intel Xeon-SP processor
 - OCP3.0 NIC
 - FPGA/GPU acceleration
 - Low latency NVMe





Front –Access including PSUs





ASUS 1U DU/CU Server

- 1-socket Intel Xeon-SP processor
- Smaller and compact chassis
- Front access design
- DC/AC-IN PSU support
- Critical environment temperature
- NEBS compliance

Progressing





ASUS Provides High Availability FW to Support 5G Server

Redundant FW Support

1. Redundant FW (BIOS/BMC) support

2. Recover from failure components and remote update lowering overall downtime

BMC

1. ASUS BMC support WEBUI, IPMI, Redfish protocols for efficient management

- OpenBMC supported
- 3. Diagnostic tool for remote debug and maintenance



PFR

- 1. Platform Firmware Resiliency supported
- 2. Check FW authentication to prevent malicious FW
- 3. Compliant with NIST regulation

Performance Tuning

- 1. Performance Tuning bundled in BIOS, easy to set for different workloads
- 2. Targeting to deliver best-fit portfolios

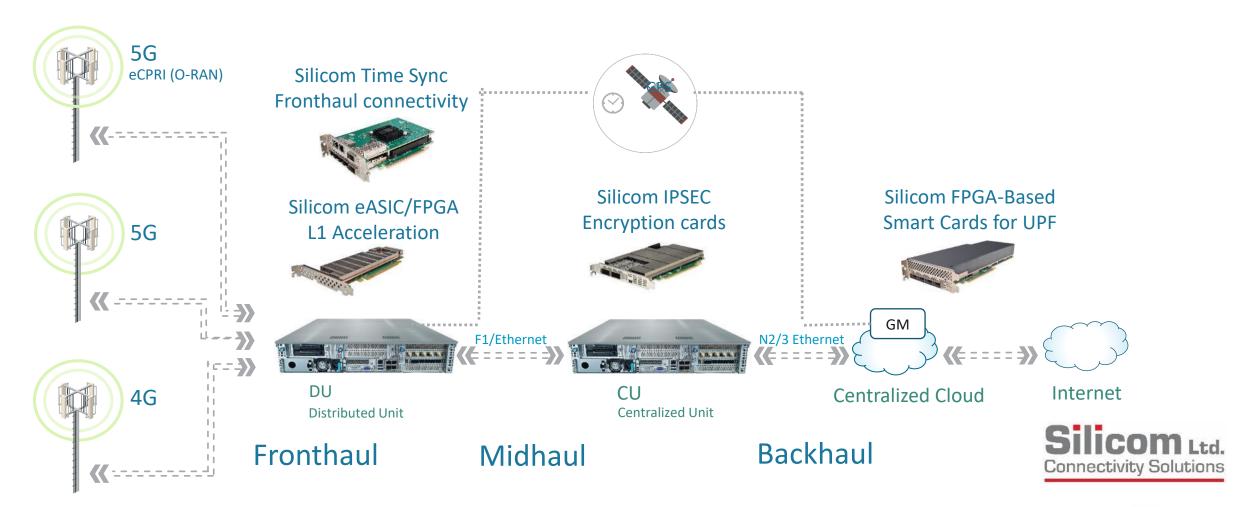
Telco Solution Compliance

- 1. RedHat Linux/Realtime compliance
- 2. Wind River studio cloud platform compliance





Silicom and ASUS Together to Offer The Perfect Solution to Accelerate 5G Market

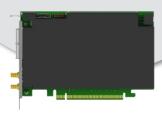




Silicom 5G PCIe cards for 4G/5G

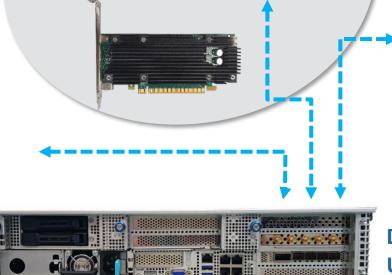
Silicom 5G SmartNIC

- FPGA Arria10/AgileX and MAC
- L1 Acceleration
- Time Sync 1588/SyncE
- OCXO for Hold Over
- 8 port 10G/25G or 2*100G
- GNSS receiver Grand Master
- Boundary / Transparent mode
- BMCA Best Master Clock Algorithm
- Support O-RAN LLS C1/C2/C3/C4



Silicom ACC100 (Pomona Lake)

- FEC Acceleration (LDPC -5G/Turbo-4G)
- Support DPDK/BBDEV
- Standard/Extended Temp versions
- BMC for Remote Management



Silicom Time Sync (STS)

- E810 Drivers
- Time Sync 1588 and SyncE
- 4, 8 and 12 ports -1G/10G/25G
- GNSS receiver Grand Master
- Boundary / Transparent mode
- Hold Over 4 to 8 hours
- BMCA Best Master Clock Algorithm
- Support O-RAN LLS C1/C2/C3/C4



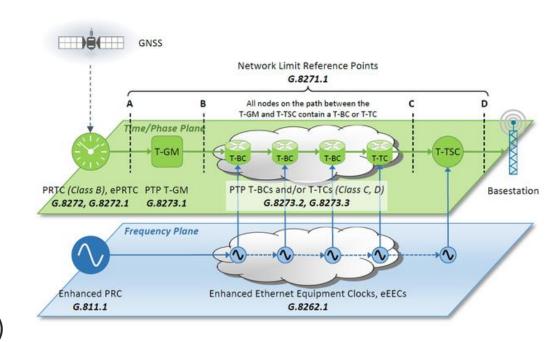
Distributed Unit







- Support 1588/PTP over IPv4 / IPV6, IEEE1588v2
- Support SyncE /ITU-T G.8262
- T-BC/T-TSC Boundary Clock and TSC Slave Clock /G.8273.2
- T-GM Grand Master /G.8273.1 per G.8275.1 PTP Profile
- PRTC Primary Reference Time Clock Class B/G.8272
- OC Own Clock(Master / Slave) Class C(Stratum 3e)
- BMCA Best Master Clock Algorithm (OCXO, SyncE, GNSS, 1588)
- Support for 1.5usec TIE at <12 Hours Hold Over
- Software 1588 Stack and Servo SW in x86





STS1 - Silicom® Time Synchronization #1

Time Sync NIC with 1588 and SyncE

Supported Time Synchronization

- PTP/1588
- SyncE
- 1PPS and 10Mhz Input
- Boundary Clock
- Grand Master/PRTC; using external GNSS Receiver
- 1PPS Output and 10Mhz Input/output Optional

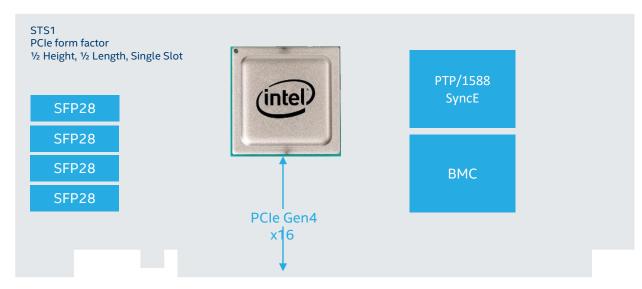
Built with Intel® E810-CAM1

- PCle Gen 4 x16
- 4x SFP28 25GbE and 10GbE
- BMC for monitoring and control over PCIe SMBus
- ½ Height, ½ Length PCle card
- Standard Temp (0°C to +45°C)
- Optimized for ~28W TDP(w/o optics)

Ordering P/N

PE425G4TSI81L-XR - Standard Temp (0°C to +45°C)







STS2 – Silicom® Time Synchronization #2

Time Sync NIC with 1588 and SyncE

Supported Time Synchronization

- PTP/1588
- SyncE/G.8262
- Boundary Clock
- Grand Master/PRTC; GNSS Receiver on board
- GNSS Antenna Input
- 1PPS Output and 10Mhz Input/output Optional

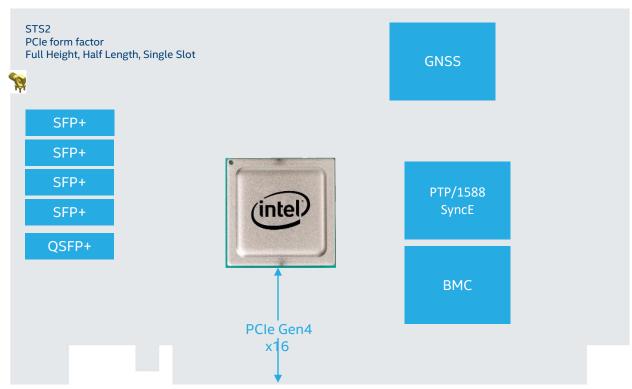
Built with Intel[®] E810-CAM2

- PCle Gen 4 x16
- 4x SFP+;1x QSFP+; 10GbE
- BMC for monitoring and control over PCIe SMBus
- Full height, ½ Length PCIe card
- Standard Temp (0°C to +45°C)
- Optimized for ~42W TDP(w/o optics)

Ordering P/N

P410G8TS81-XR - Standard Temp (0°C to +45°C)







Silicom® eASIC® Pomona Lake

FEC offload for vRAN

Supported through Intel® DPDK, BBDEV

FEC Offload

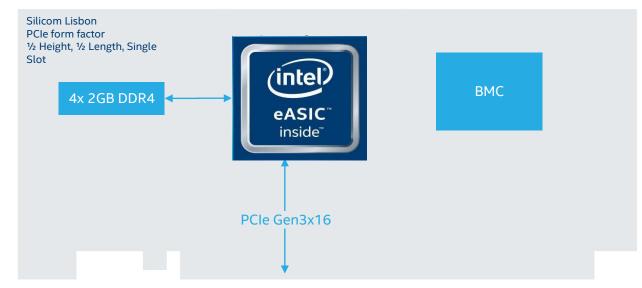
Built with Intel® Mount Bryce

- Turbo(4G) and LDPC(5G)
- Lookaside Accelerator
- Part of FlexRAN L1 SW, Version 20.08
- PCle 3.0 x16
- BMC for monitoring and control
- 1/2 Height, 1/2 Length, PCle
- OCP2.0 SFF
- Standard and Industrial Temp (-20°C to +55°C)
- Optimized for ~40W TDP

Ordering P/N

- P3iMB-M-P1 Standard Temp (-5°C to +45°C)
- P3iMB-M-P2 Extended Temp (-20°C to +55°C)
- O3iMB-P2 OCP 2.0 SFF Extended Temp (-20°C to +55°C)







Silicom® FPGA SmartNIC - Oakham

Smart NIC For Comms Service Providers

High performance networking acceleration card

Programmable through Intel® DPDK

Accelerated Workloads

vRAN

Built with Intel® Aria 10 GT FPGA

- High speed Ethernet support: 10G and 25G
- PCle Gen 3 x16
- 4GB DDR4 memory
- 1588, SyncE and GNSS
- BMC for monitoring and control (PLDM)
- ½ length, full height
- Optimized for ~75W TDP

Supports Dual Intel® Ethernet Controller XL710

- Extensive OS support and easier system integration
- Dual 40Gbps pipeline



